

Title (en)
COMPONENT AND METHOD FOR PRODUCTION THEREOF

Title (de)
BAUELEMENT UND VERFAHREN ZUM HERSTELLEN DES BAUELEMENTS

Title (fr)
COMPOSANT ET PROCEDE DE FABRICATION ASSOCIE

Publication
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Application
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Priority

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Abstract (en)
[origin: DE19747846A1] The invention relates to a component and to a method for the production thereof. Said component is more particularly an electronic component with a micro electronic chip and a carrier which is produced by means of isothermal coagulation.

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H01L 21/607

IPC 8 full level
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